

WHAT WE CLAIM IS:

1. A thin-film EL device having at least a structure comprising an electrically insulating substrate, a patterned electrode layer stacked on said substrate, and a dielectric layer, a light-emitting layer and a transparent electrode stacked on said electrode layer, wherein:

said dielectric layer is a multilayer dielectric layer formed in a multilayer form by repeating a solution coating-and-firing step plural times, and

said multilayer dielectric layer has a thickness of at least four times as large as a thickness of said electrode layer and 4 μm to 16 μm inclusive.

2. The thin-film EL device according to claim 1, wherein said multilayer dielectric layer is formed by repeating said solution coating-and-firing step at least three times.

3. The thin-film EL device according to claim 1, wherein said multilayer dielectric layer has a thickness per sub-layer of at least 1/2 of said electrode layer.

4. A process of fabricating a thin-film EL device having at least a structure comprising an electrically insulating substrate, a patterned electrode layer stacked on said substrate, and a dielectric layer, a light-emitting layer and a transparent electrode stacked on said electrode layer, wherein:

said dielectric layer is provided on said electrode layer in a multilayer form by repeating coating-and-firing of a dielectric precursor solution plural times.

5. The process of fabricating a thin-film EL device according to claim 4, wherein the coating-and-firing of said dielectric precursor solution is repeated at least three times.